

SUMMARY LISTING OF CLAIMS

Claims 1-2	(Cancelled)
Claim 3	(Currently amended)
Claim 4	(Cancelled)
Claim 5	(Withdrawn)
Claim 6	(Withdrawn)
Claim 7	(Original)
Claim 8	(Cancelled)
Claim 9	(Currently amended)
Claim 10-12	(Cancelled)
Claim 13-17	(Withdrawn)
Claim 18	(Cancelled)
Claim 19	(Withdrawn)
Claim 20	(Cancelled)
Claim 21	(New)
Claim 22	(New)

AMENDMENTS TO THE CLAIMS

Please cancel Claims 1, 2, 4, 8, 10-12, 18 and 20 without prejudice.

3. (Amended) The semiconductor device of Claim 21, wherein said second surface has a smaller area than said first surface.
7. (Original) The semiconductor device of Claim 3, wherein there are two hand leads.
9. (Amended) The semiconductor device of Claim 21, wherein the resin encapsulated body contains a tab sealed therein.
21. (Added) A semiconductor device, comprising:
 - a plurality of leads having a top surface, a bottom surface, two side surfaces, and two end surfaces, said leads having a square cross section shape perpendicular to the longitudinal direction of the leads;
 - a resin encapsulated body having a first surface, a second surface opposite said first surface, and four side surfaces through which said leads project,
 - each of said leads comprises a first area wherein all of said top surface, bottom surface, and two side surfaces are covered by said resin encapsulated body, a second area wherein said top surface is covered by said resin encapsulated body and said bottom surface and said two side surfaces are exposed from said resin encapsulated body, and a third area wherein said top surface, bottom surface, two side surfaces, and two end surfaces are exposed from said resin encapsulated body.
22. (Added) A semiconductor device according to Claim 3, wherein each of said hang leads has a top surface, a bottom surface, two side surfaces, and two end surfaces, and comprises a first area wherein all of said top surface, bottom surface, and two side surfaces are covered by said resin encapsulated body, a second area wherein said top surface is covered by said resin encapsulated body and said bottom surface and said two side surfaces are exposed from said resin encapsulated body, and a third area wherein said top surface, bottom surface, two side surfaces, and two end surfaces are exposed from said resin encapsulated body.